






用途・目的別に対応したボンディングワイヤ

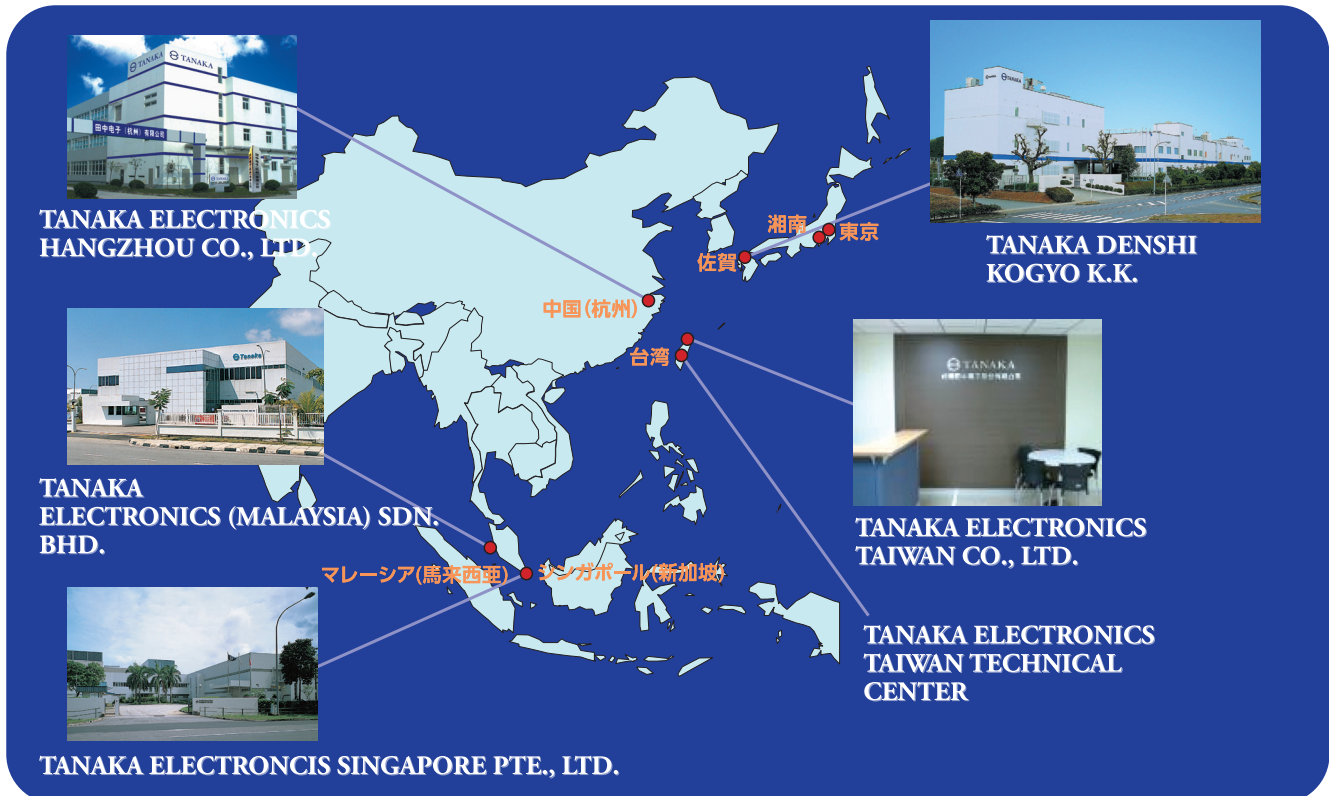
Bonding Wires for various applications

素材別のワイヤ材料との接合性

		Wire Bondability for each Material				
		Bonded Material				
Wire Material		Cu	Au/Pd/Ni Plating	Ag Plating	Ni Plating	Al
Au Alloy		★★★★☆ Good	★★★★☆ Good	★★★★★ Excellent	★☆☆☆☆ No Good	★★★★☆ Good
Pd Coated Cu		★★★★☆ Good	★★★★☆ Good	★★★★★ Excellent	★☆☆☆☆ No Good	★★★★☆ Not recommended
Cu Alloy		★★★★☆ Good	★★★☆☆ Not recommended	★★★★★ Excellent	★☆☆☆☆ No Good	★★★★☆ Not recommended
Ag Alloy		★★★★☆ Good	★★★★☆ Good	★★★★★ Excellent	★☆☆☆☆ No Good	★★★★☆ Good
Al		★★★☆☆ Not recommended	★★★☆☆ Not recommended	★★★★☆ Not recommended	★★★★★ Excellent	★★★★☆ Good

グローバルネットワークによるタイムリーなサポート体制

Timely support by global network



The map highlights the following global network locations:

- TANAKA ELECTRONICS HANGZHOU CO., LTD.** (中国(杭州))
- TANAKA DENSHI KOGYO K.K.** (東京)
- TANAKA ELECTRONICS (MALAYSIA) SDN. BHD.** (マレーシア(馬來西亞))
- TANAKA ELECTRONICS TAIWAN CO., LTD.** (台湾)
- TANAKA ELECTRONICS TAIWAN TECHNICAL CENTER** (台湾)
- TANAKA ELECTRONICS SINGAPORE PTE., LTD.** (シンガポール(新加坡))

